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THE WORLDWIDE IC PACKAGING MARKET

2015 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis

- **Worldwide IC Packaging Market Forecasts, 2013–2019**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range

- **OSAT IC Packaging Market Forecasts, 2013–2019**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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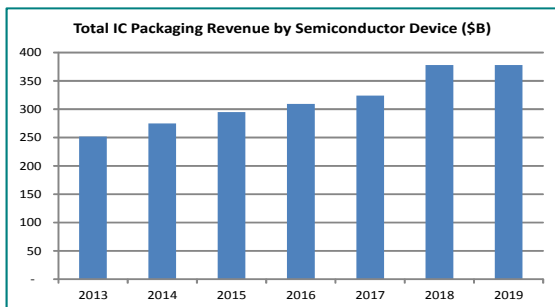
The Worldwide IC Packaging Market, 2015 Edition

Synopsis

While the integrated circuit (IC) market tends to be cyclical in nature, the general trend is for more ICs to be integrated into more products over time. The market is being driven by demand for handheld consumer devices as well as advanced computing products. All product segments (consumer, computer, communications, transportation, industrial) are benefiting and leading to new product innovation.

Following an unexpectedly robust year of growth (9.2%), in 2014, the semiconductor industry moderated its expansion in the first half 2015. While the rate of growth for both semiconductors shipped and worldwide revenues will decline somewhat in the second half of 2016 (election year), the market is expected to post a respectable CAGR of 4.2% over the next five years.

New Venture Research (NVR), in the **2015 Edition** of **The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market by package type and application. The report begins with an economic and industry overview, then examines the historic and future unit and revenue IC growth.



Source: SIA and NVR estimates

Following this high-level review, the report presents forecasts for the total worldwide IC packaging marketplace (Chapter 4), and explains the market segmentation defined by NVR. Next, the report dives deeply into an analysis of each semiconductor product type (Chapter 5), and segments these products by package family, I/O count range and general market application. The analysis returns to the individual package families (Chapter 6) and presents each in terms of semiconductor devices and I/O count. In all tables, unit shipments and revenue figures are displayed for each segment.

Next, the report presents *NVR's* continuing coverage of the outsourced semiconductor assembly and test (OSAT) market. These companies already comprise a significant share of the worldwide IC packaging market and will continue to grow in importance in the coming years. The report presents the total OSAT market in terms of both unit shipments and revenues. To help you further assess this group of companies, the report profiles the activities of the leading OSAT companies and the packages they offer.

The Worldwide IC Packaging Market, 2015 Edition continues *NVR's* leadership position in assessing the status and future of IC packaging. This report is an effective and economical tool for any company associated in the semiconductor industry to aid in assessing their own markets and potential areas of growth. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is \$1500. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$1000 and a printed copy for \$250.

About the Author

Jerry Watkins is an independent senior analyst with more than 17 years of experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing and merchant embedded computing industry. He holds three university degrees including a B.A. in History, as well as a M.A. in International Studies.

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Package Type	I/O Count Range
DIP	004-018
SOT	020-032
SO	034-100
TSOP	104-304
DFN	308-999
CC	1,000+
QFP	
QFN	Average Price by Package Type
PGA	
BGA	
FBGA	
WLP	
DCA	

Chapter 5: IC Package Market Analysis and Forecasts by Semiconductor Device - 2013-2019

Device Types: Package Types: I/O Count:

Device Types	Package Types	I/O Count
MPU	DIP	004-018
MCU	SOT	020-032
DSP	SO	034-100
DRAM	TSOP	104-304
Flash	DFN	308-999
SRAM	CC	1,000 +
ROM/EPROM	QFP	
EEPROM/Other	QFN	
Digital Bipolar	PGA	
Standard Logic	BGA	
Gate Arrays	FBGA	
Standard Cell/PLD	WLP	
Display Drivers	DCA	

Special Purpose Logic and Application Specific
Analog - All Segments
Device Application Trends

Chapter 6: IC Package Market Analysis and Forecasts by Packaging Family - 2013-2019

Overview

Dual In-line Package Markets

Small Outline Transistor Markets

Small Outline Markets

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Dual Flat Pack No Lead Markets

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Quad Flat Pack Markets

Quad Flat Pack No Leads Markets

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3D Plus, Inc.

Advotech

AIC Semiconductor

Amkor

Anst China

ASE

Azimuth

Carsem

Chant World Technology

China Wafer Level CSP

ChipMOS

Cirtek

CONNECTEC Japan

CORWIL Technology

Deca Technologies

FlipChip Int'l

Greatek Electronics

HANA Microelectronics

HANA Micron

I2a Technology

J-Devices

Jiangsu Changjiang

Lingsen Precision

NANIUM

Nantong Fujitsu

OSE

Powertech

Shinko Electric

Signetics

Sigurd

Siliconware

SPEL

STATS ChipPAC

Tera Probe

Tianshui Huatian Tech

Unisem

UTAC

Vigilant Technology

Walton Advanced Eng.

Xintec

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Package Price Forecasts	Thin Small Outline Packages
IC Product Forecasts	TSOP Forecasts—3 I/O Ranges
MPU	Dual Flat Pack No Lead Packages
MCU	DFN Forecasts—2 I/O Ranges
DSP	Chip Carrier Packages by Device
DRAM	Chip Carrier Forecasts—2 I/O Ranges
Flash	Quad Flat Packs by Device
SRAM	QFP Forecasts—2 I/O Ranges
ROM and EPROM	Quad Flat Pack by Device
EEPROM/Other Memory	QFN Forecasts—4 I/O Ranges
Digital Bipolar	Pin Grid Arrays by Device
Standard Logic	PGA Forecasts—2 I/O Ranges
Gate Arrays	Ball Grid Array Packages by Device
Cell-Based and PLD	BGA Forecasts—4 I/O Ranges
Display Drivers	Fine Pitch Ball Grid Array by Device
Special Purpose Logic	FBGA Forecasts—6 I/O Ranges
Amplifiers	Wafer Level Packages by Device
Interfaces	WLP Forecasts—4 I/O Ranges
Voltage Regulators	Direct Chip Attach ICs by Device
Data Converters	
Application Specific Analog	OSAT Total Forecast
	Packaging OSAT Rankings

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